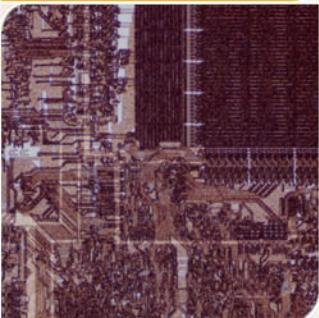


# CS4290/CS6290

Fall 2011

Prof. Hyesoon Kim



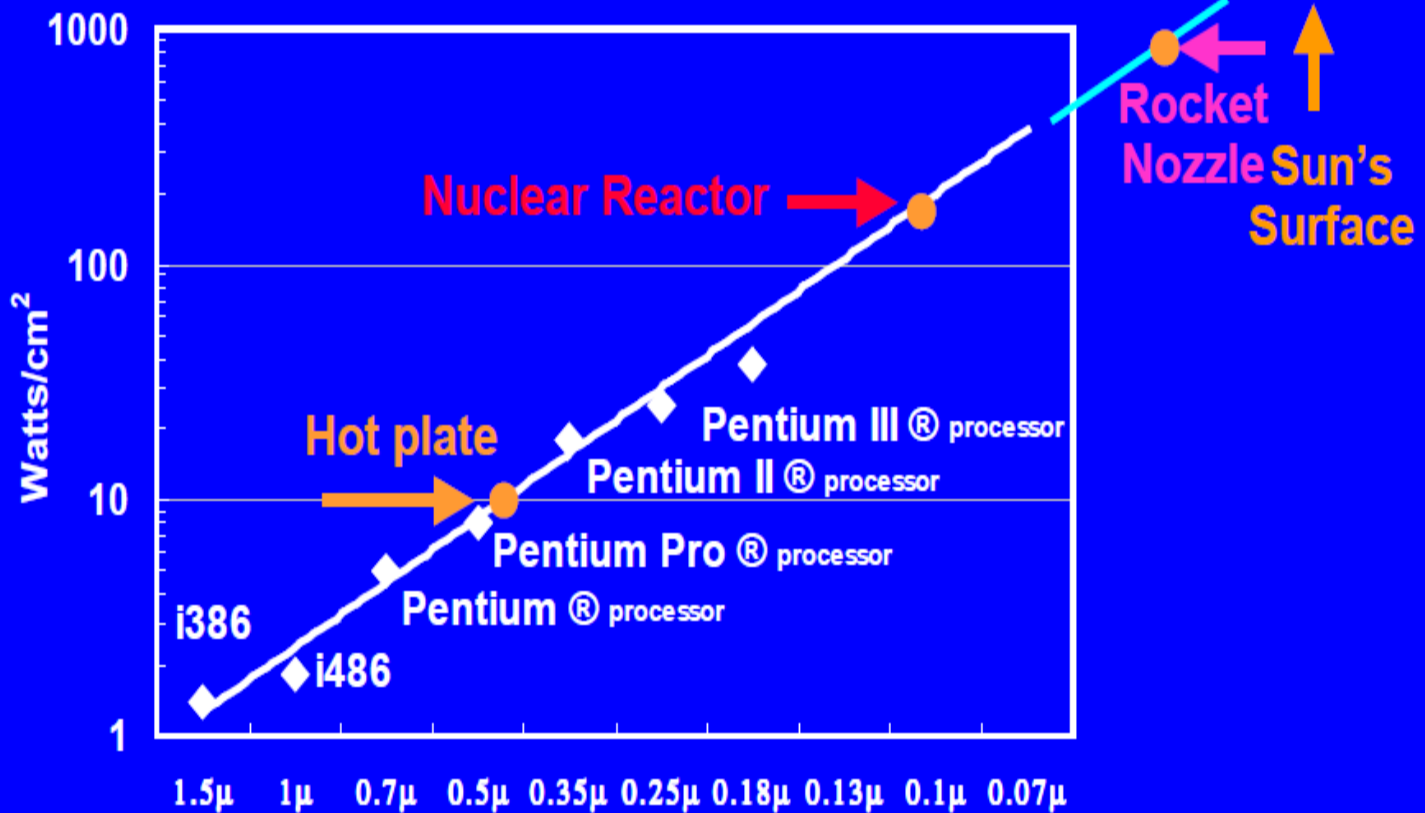
**Georgia  
Tech**



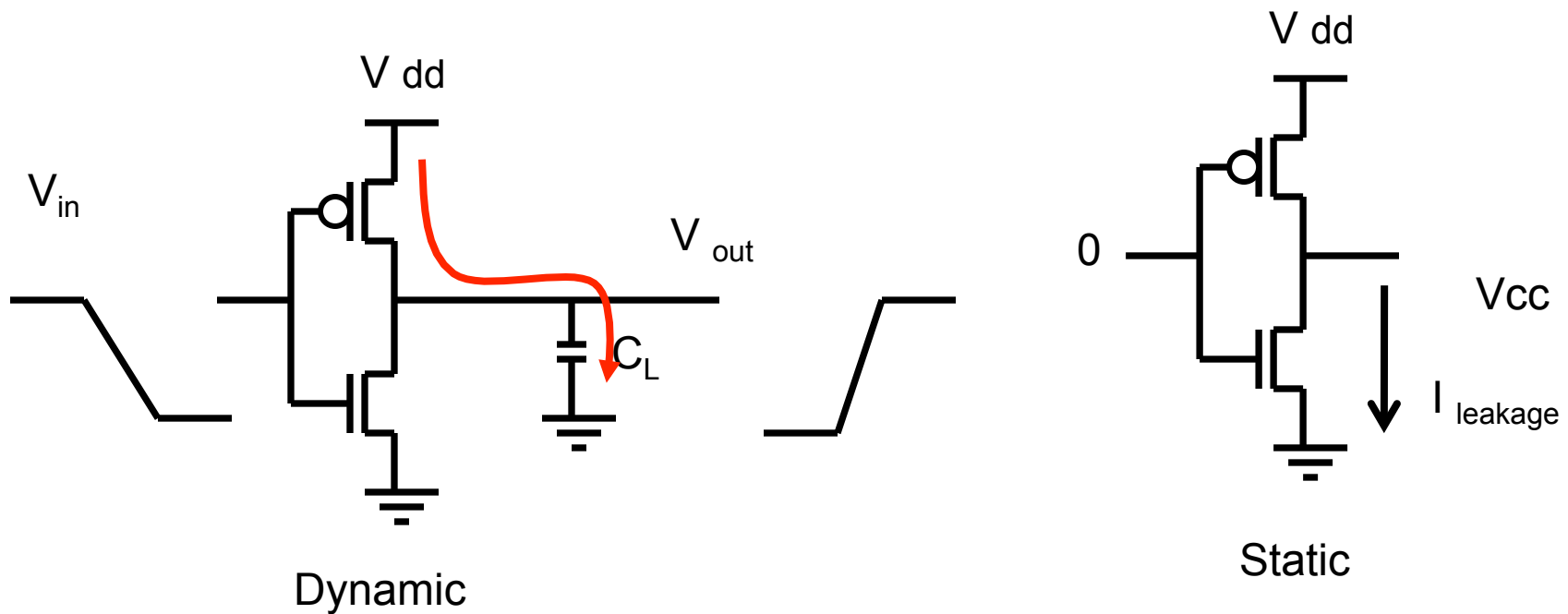
College of  
Computing

# Why Power?

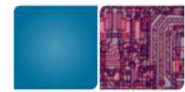
## Power density continues to get worse



# Power Dissipation in CMOS

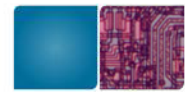


$$P_{tot} = P_{dyn} + P_{sta} = C_L V_{dd}^2 f + V_{dd} I_{leak}$$



# Power Basics

- Power vs. Energy
- Dynamic power vs. Static power
  - Dynamic: “switching” power
  - Static: “leakage” power
  - Dynamic power dominates, but static power is increasingly important

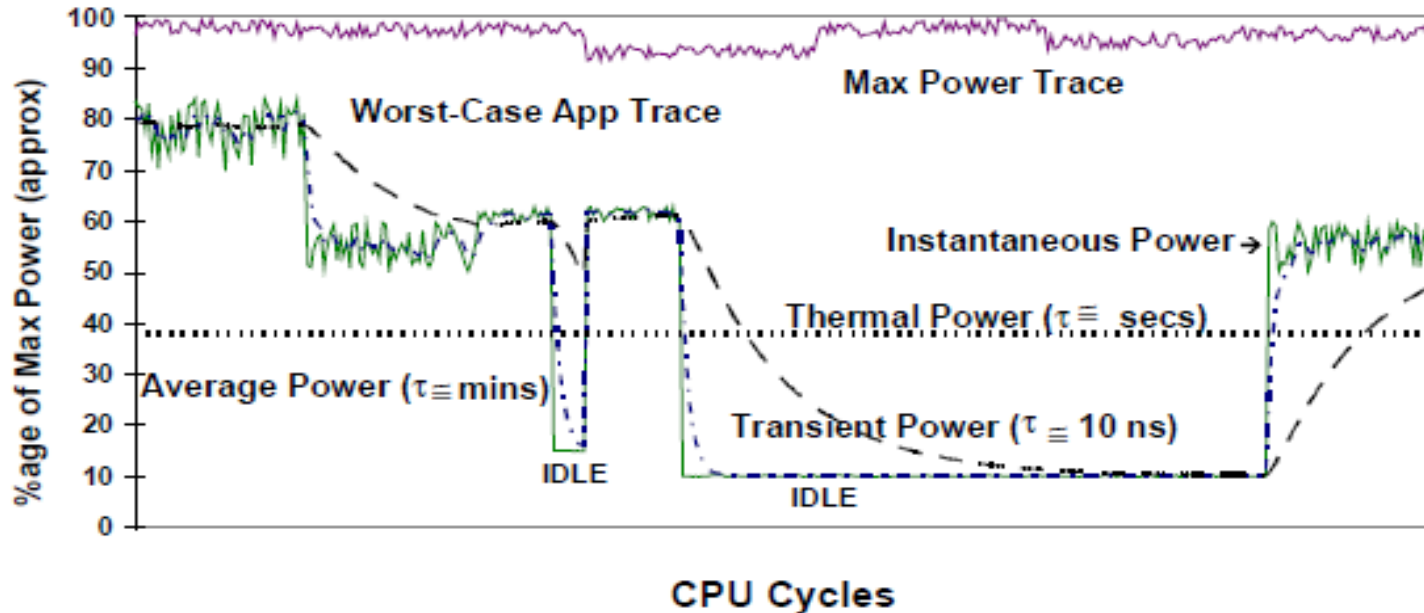


# Why do we care?

- 1) Increase the CPU cost
  - Thermal cost: keeping the devices below the special temperature
- 2) the cost of power delivery

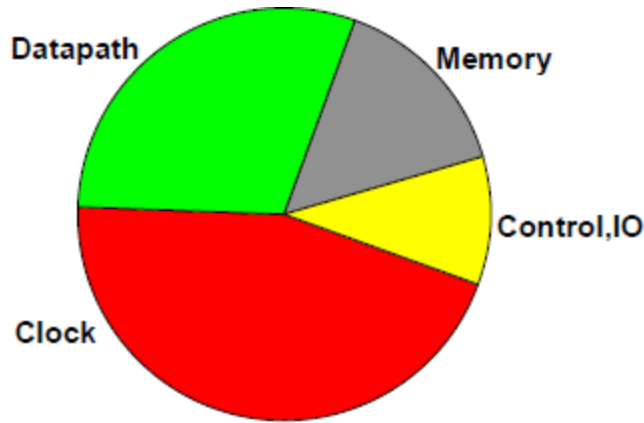


# Power power power



- Max Power
- Worst-case application
- Average power
- Thermal power: running average of worst-case app for several seconds : used to decide cooling option
- Transient power (power delivery) , standby power (battery life),

# Where does Power Go?



Clock power consumption is high  
Even when AF is 0.5

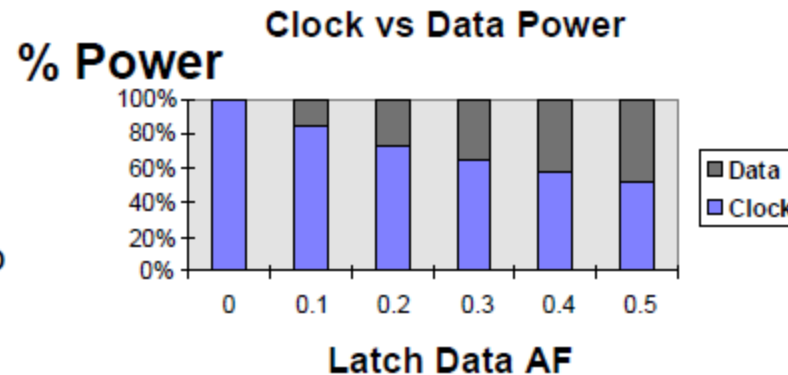
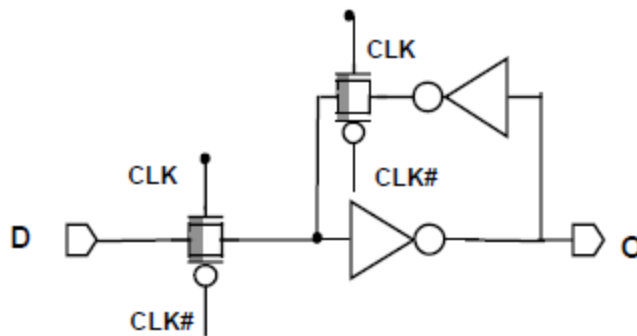
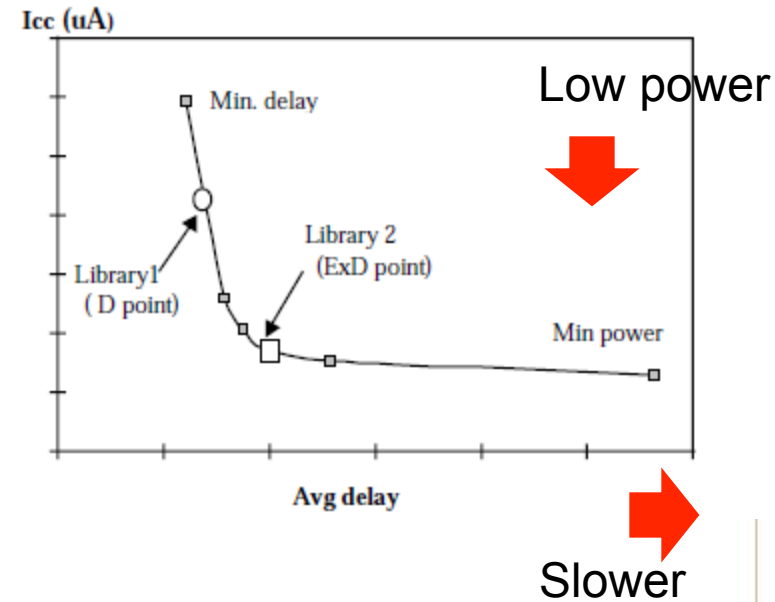


Figure 5: Power consumption in latches AF (activity factor)



# Power Reduction Techniques

- Voltage scaling
- Clock gating
- Utilize circuit design techniques
- Low power logic synthesis
  - Non-critical path → low power circuit (slow but so what? )
- Specific circuit technology
  - Reduce AF (domino circuit)





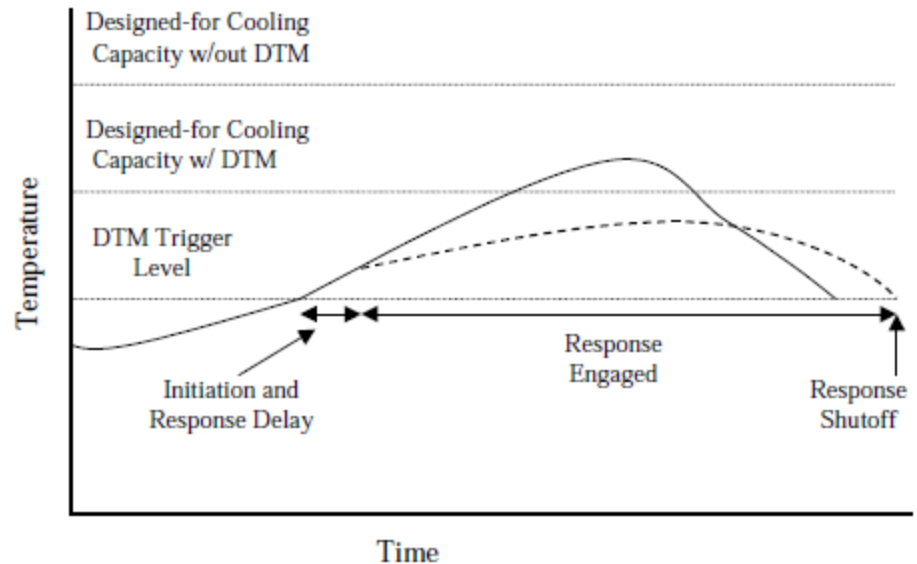


# DVS (Dynamic Voltage Scaling)

- O/S controls the processor speed: find the minimum voltage required for the desired speed.
- DVFS (Dynamic Voltage Frequency Scaling): Intel's CPU throttling technology, SpeedStep

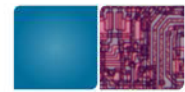
# DTM (Dynamic Thermal Management) Techniques

- DTM: software and hardware techniques at run-time to control a chip's operating temperature
- Thermal package is designed for normal operating conditions rather than worst case
- Key goals:
  - To provide inexpensive hardware/software responses
  - Reduce power
  - Reduce impacts on performance as little as possible



Dynamic Thermal Management for High-Performance Microprocessors,  
Brooks and Martonosi (01)

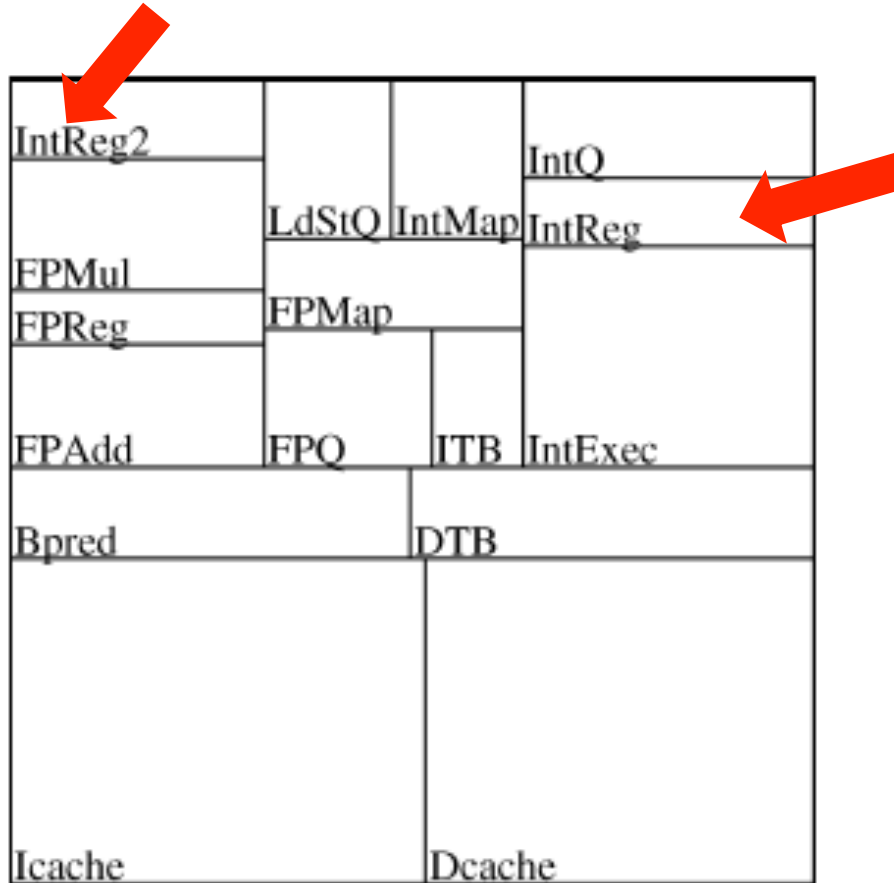
# DTM



- Trigger mechanisms
  - Temperature sensors, on-chip activity counters
- DTM Response mechanisms
  - Clock frequency scaling
  - Voltage and frequency scaling
  - Decode throttling (PowerPC G3)
  - Speculation control
  - I-cache toggling (disabling instruction cache)
  - Migration computation



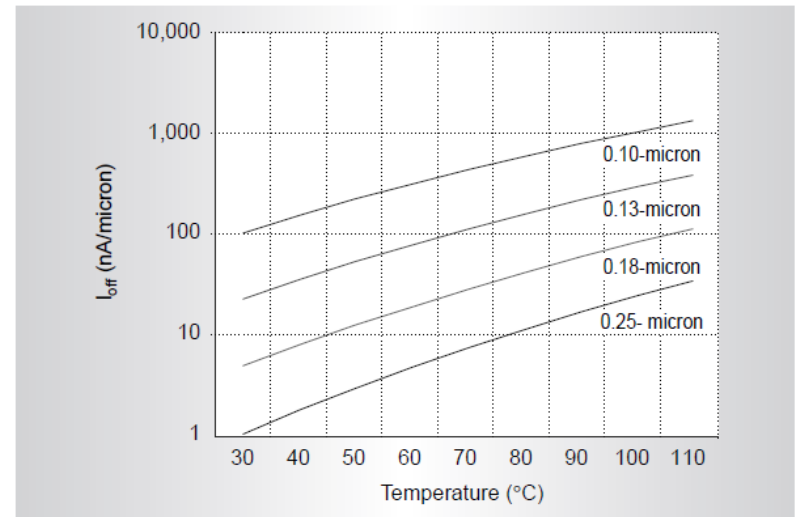
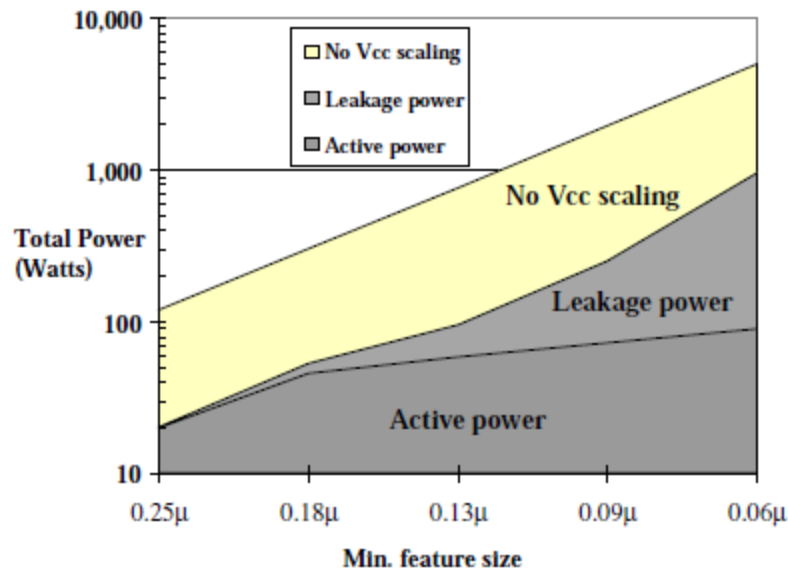
# DTM: Migration Computation



- Spare unit is located in cold area of chip
- Primary unit reaches 81.6C, issue is stalled, instructions ready to write back is allowed.
- All instructions use second register file.
- When the primary register file reaches 81.5C the process is reversed



# Leakage Power Trend



- Technology scales, leakage power consumption is increased
- Leakage power/current increases as temperature increases

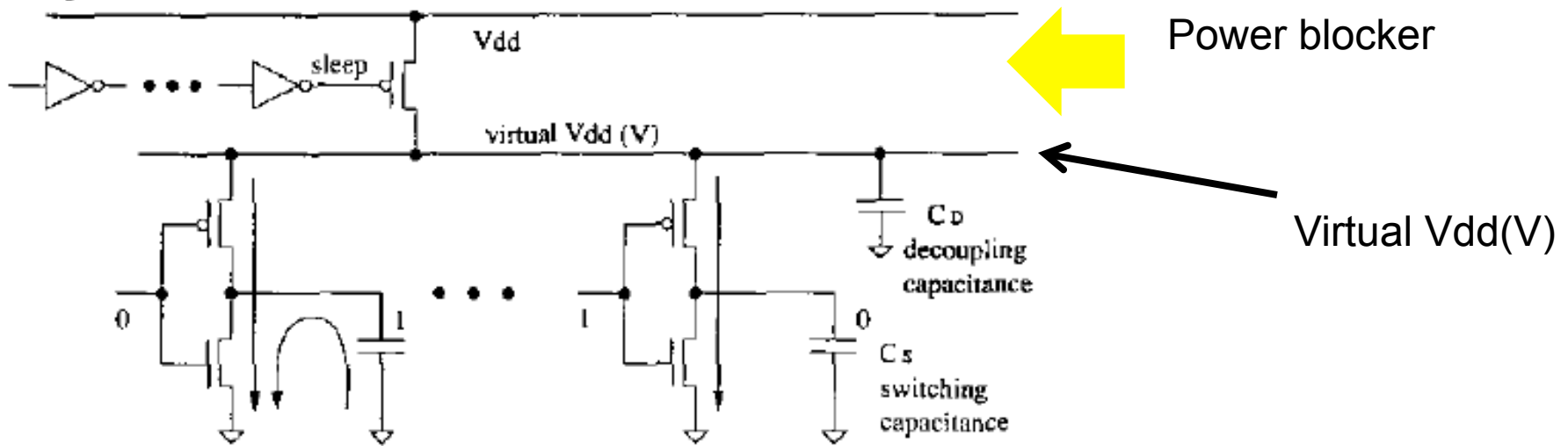


# Leakage Power Control Techniques

- Body-bias control
- Dual-threshold domino circuits
- Input vector control (by inputting all 0's for a NAND gate)
- Power gating

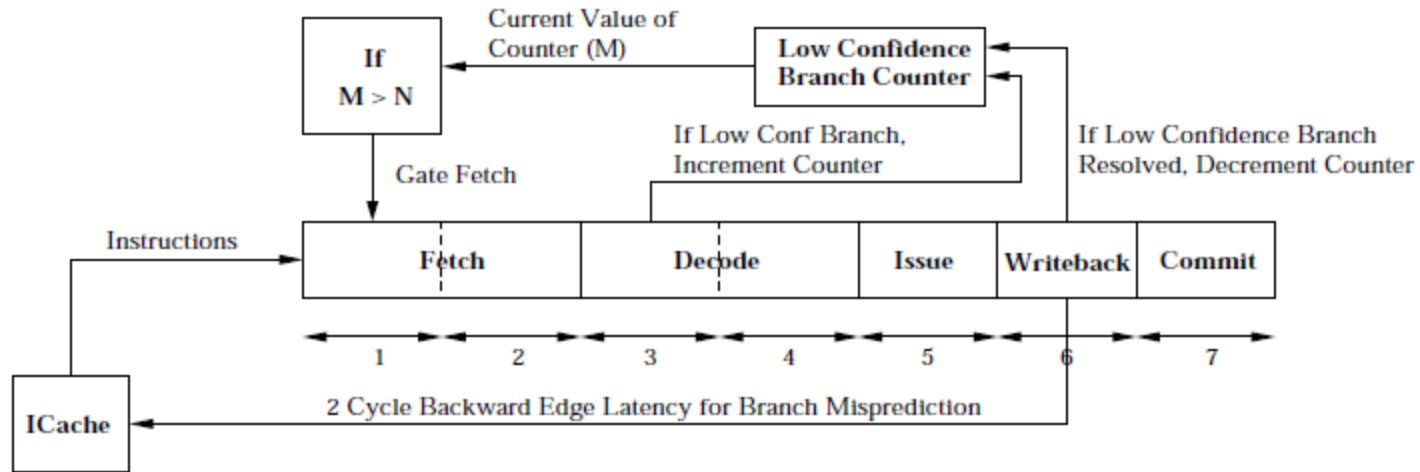


# Power Gating



- Sleep signal to turn off the supply voltage
- Save both dynamic power and leakage power

# Pipeline Gating (Manne et al. '98)



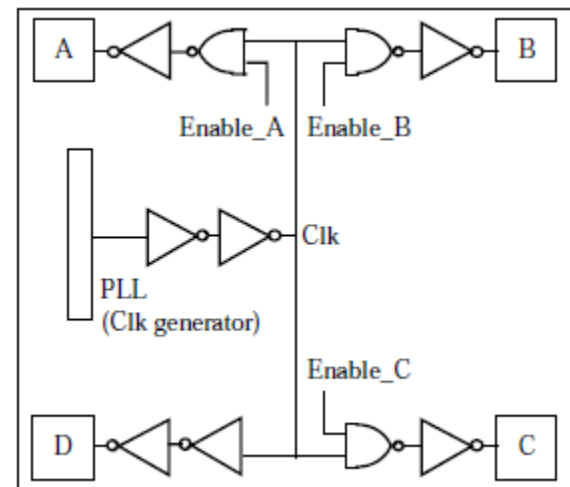
- Determine when a branch is more likely mispredicted and gate a pipeline
- Use confidence estimator
- Other metrics (number of instructions)
- JVM





# Clock Gating

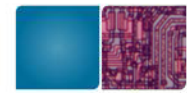
- Adds additional logic to a circuit to prune the clock tree
- Reduce dynamic power consumption
- Power up delay (timing problem)
- Variations in current



# Benefits of Power Gating and Clock Gating

## Gating

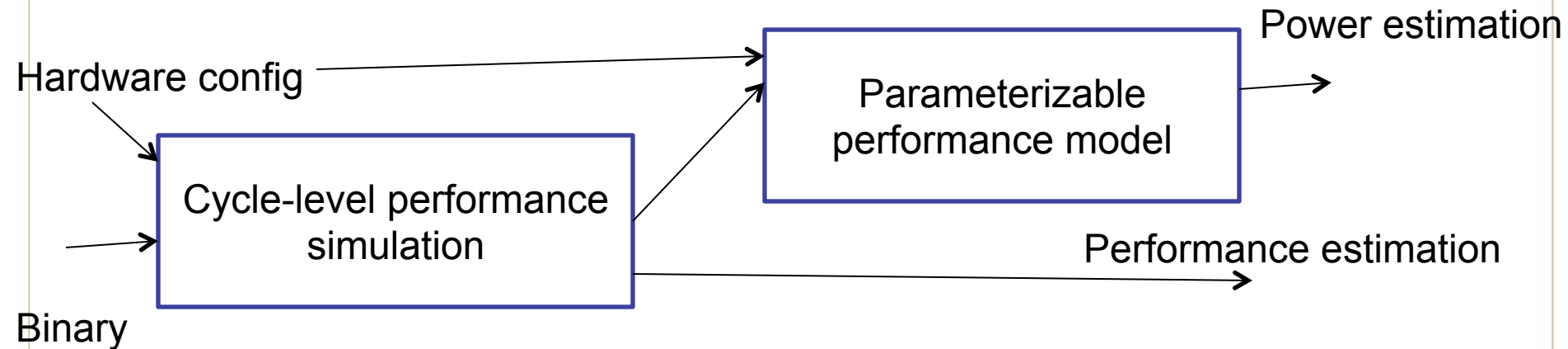
- Clock Gating → reduce dynamic power consumption but not the static power consumption
- Power gating → eliminate both dynamic and static power consumption



# Architecture Power Simulators

- SimpleScalar ( Performance simulator)
- Wattch : Dynamic Power Simulator
- HotLeakage: Leakage current simulator
- HotPower: thermal spot
- MacPat:

# Wattch (Brooks et al. '00)

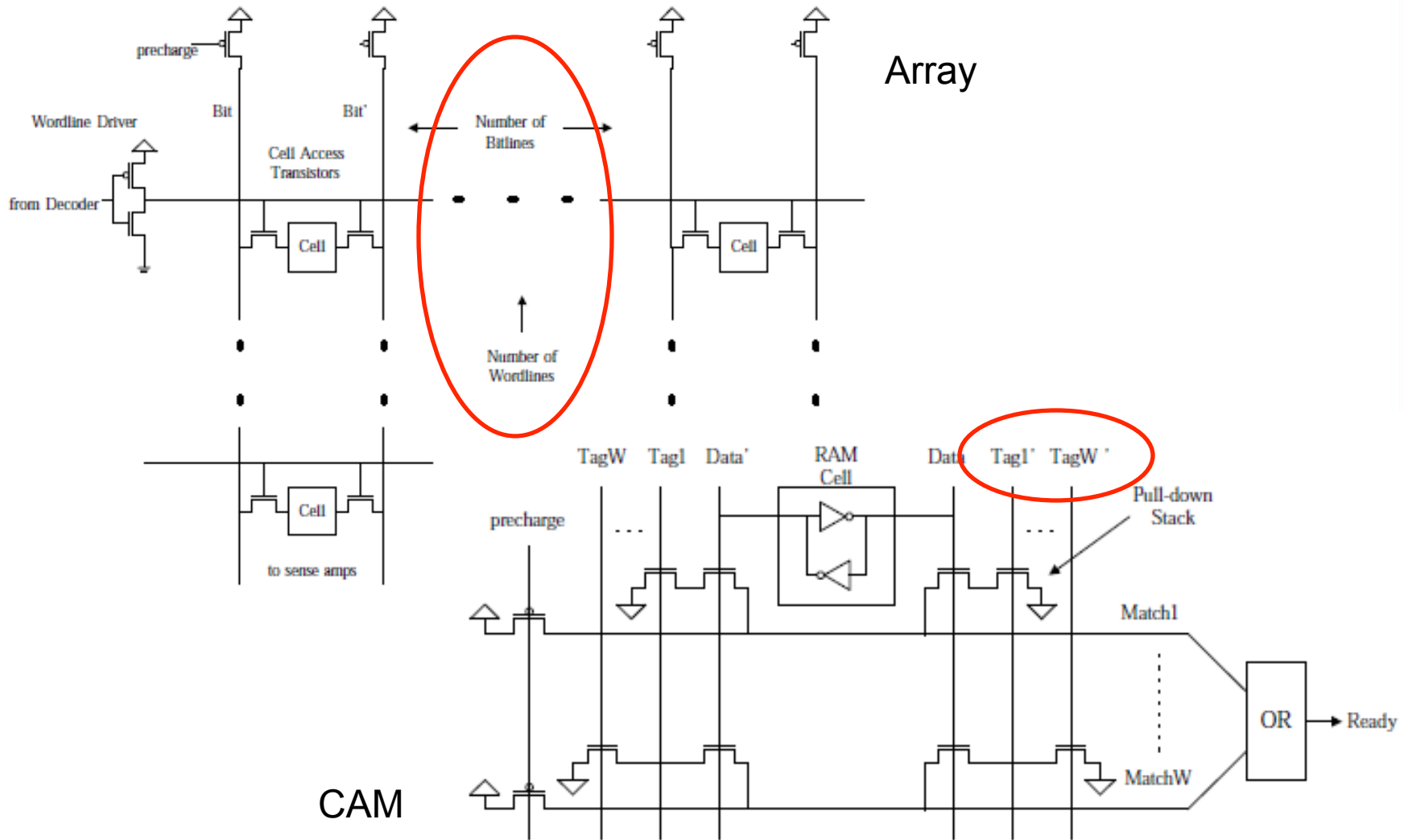


$P_d = C_v V_{dd}^2 a f$  C: load capacitance, V<sub>dd</sub>: supply voltage, f: clock frequency

A: switching activity

- Array structures
- Fully associative content-addressable memories (CAM)
- Combinational logic and wires
- Clocking

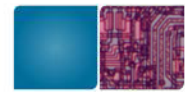
# Array structure vs. CAM





# Hardware Structures in Wattch

Hardware structures	Model Type
Instruction cache	
Wakeup logic	
Issue selection logic	
Instruction window	
Branch predictor	
Register file	
TLB	
Load/Store Queue	
Data Cache	
Integer functional units	
FP functional units	
Global clock	



# Metrics

- Power
- Energy
- EDP (Energy Delay Product)
- EDDP (Energy Delay<sup>2</sup> Product) : more emphasis on performance
- EPI (Energy per instructions)

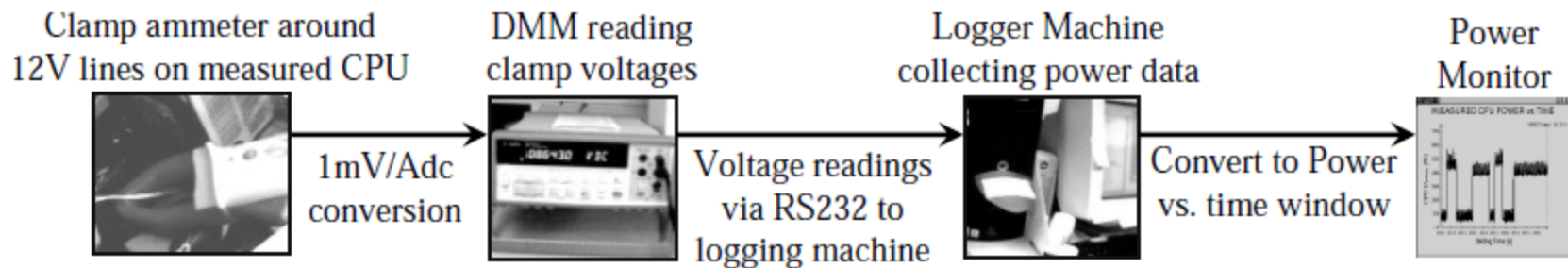


# Review: Performance vs. Power

- Cooling capacity also decides the maximum power
- Back-of-the-Envelope calculation:
  - 3.8 GHz CPU at 100W
  - Dual-core: 50W per CPU
  - $P \propto V^3$ :  $V_{\text{orig}}^3/V_{\text{CMP}}^3 = 100\text{W}/50\text{W} \rightarrow V_{\text{CMP}} = 0.8 V_{\text{orig}}$
  - $f \propto V$ :  $f_{\text{CMP}} = 3.0\text{GHz}$



# Runtime Power Monitoring



- Measuring current
- Real time power monitoring
- $\text{Power}(Ci) = \text{AccessRate}(Ci) * \text{architecturalScaling}(Ci) * \text{MaxPower}(Ci) + \text{NongatecClockPower}(Ci)$
- $\text{MaxPower} \rightarrow$  proportional to area
- $\text{Accessrate} \rightarrow$  dynamic events
- $\text{MaxPower}$ ,  $\text{architecturalScaling}$ ,  $\text{NongatedClockPower}$ : found out from empirical data



# Examples of Processor Components

- Access Rate calculation
- Use hardware performance counters to get events

Bus Control	$\frac{IOQ\ Allocation}{\Delta Cycles_1} + \frac{Bus\ Ratio \cdot FSB\ Data\ Activity}{\Delta Cycles_2}$
Front End BPU	$\frac{8 \cdot ITLB\ Reference}{\Delta Cycles_1} + \frac{Branch\ Retired}{\Delta Cycles_2}$
Secondary BPU	$\frac{Branch\ Retired}{\Delta Cycles_2}$
L1 Cache	$\frac{Ld\ Port\ Replay + St\ Port\ Replay}{\Delta Cycles_1} + \frac{Front\ End\ Event}{\Delta Cycles_2}$
MOB	$\frac{MOB\ Load\ Replay}{\Delta Cycles_2}$
Trace Cache	$\frac{Uop\ Queue\ Writes}{\Delta Cycles_1}$
Integer Execution	$2 \cdot \left( \frac{Uop\ Queue\ Writes}{\Delta Cycles_1} - FP\ Exe.\ Access\ Rate \right) - L1\ Cache\ Access\ Rate - \frac{Branch\ Retired}{\Delta Cycles_2}$
L2 Cache	$\frac{BSQ\ Cache\ Ref}{\Delta Cycles_1}$
DTLB	$L1\ Cache\ Access\ Rate + MOB\ Access\ Rate$
ITLB	$\frac{ITLB\ Ref}{\Delta Cycles_1} + \frac{BPU\ Fetch\ Req}{\Delta Cycles_2}$

- Use train benchmarks to stress particular units
- Pentium 4 based design
- Different architectures have different units



# Max Power Calculation

$$\text{Runtime\_power\_component} = \text{AccessRate} \times \text{MaxPower}$$

- **Allowable** maximum power consumption per arch. unit

## Training benchmarks

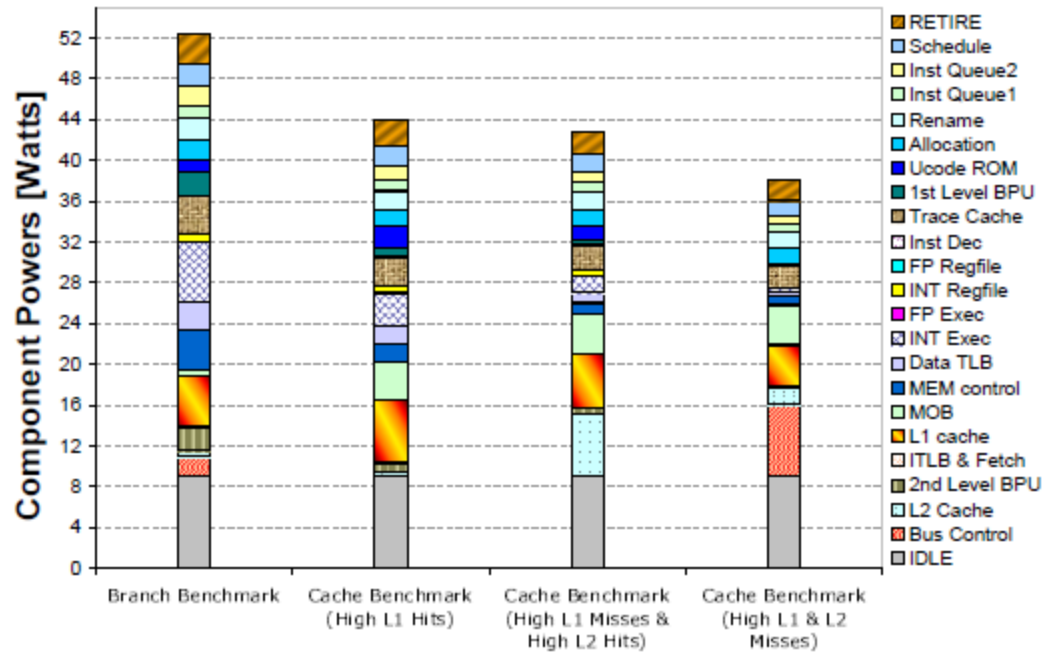
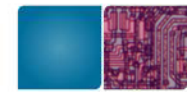
Bus control
Branch predictor
L1 cache
MOB (MSHR)
Trace cache
Integer Unit
L2 cache

$$\begin{matrix} P_1 \\ P_2 \\ P_3 \\ \cdot \\ \cdot \\ \cdot \\ P_n \end{matrix} = \begin{matrix} AR_{1A} & AR_{1B} & \dots & AR_{1Z} \\ AR_{2A} & AR_{2B} & \dots & AR_{2Z} \\ AR_{3A} & AR_{3B} & \dots & AR_{3Z} \\ \cdot & \cdot & \cdot & \cdot \\ \cdot & \cdot & \cdot & \cdot \\ \cdot & \cdot & \cdot & \cdot \\ AR_{nA} & AR_{nB} & \dots & AR_{nZ} \end{matrix} \times \begin{matrix} M_A \\ M_B \\ M_C \\ \cdot \\ \cdot \\ \cdot \\ M_Z \end{matrix}$$

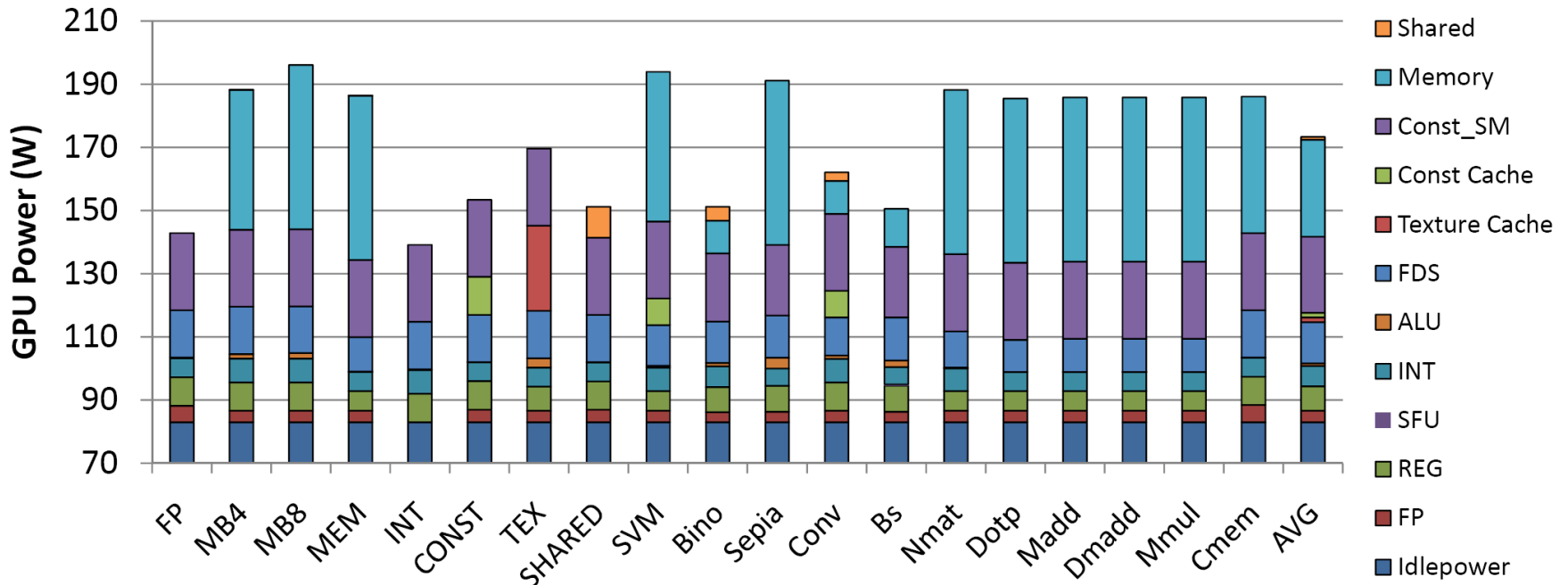
**Measured Power**
**AccessRate**
**Maximum power per arch. unit**

**Solve** for the set of **MaxPower** values  $(M_A, M_B, \dots, M_Z)$

# Power Breakdowns



# GPU Power Breakdown

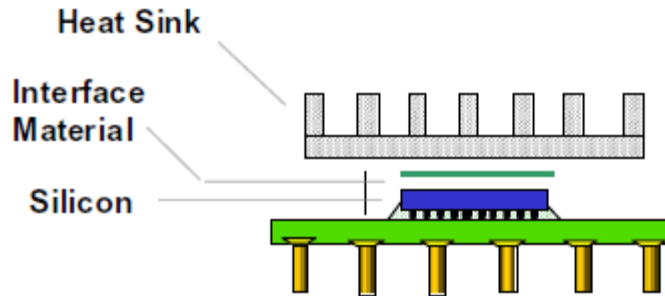




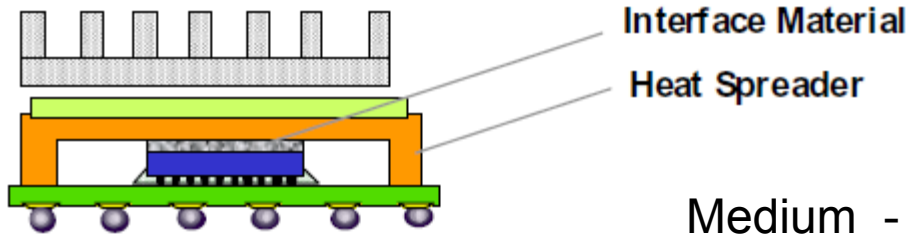
# Hardware Performance Counters

- Built in counters inside hardware
- Example counters
  - Branch misprediction, cache misses, retired instructions, pipeline bubbles, DRAM traffics
  - 10s (even 100s) of even counters, but typically only few can be read simultaneously
- Software
  - Typically windows/Linux (Linux requires kernel recompilation)
  - PAPI, PerfMon, Vtune, etc.

# Heat Sink

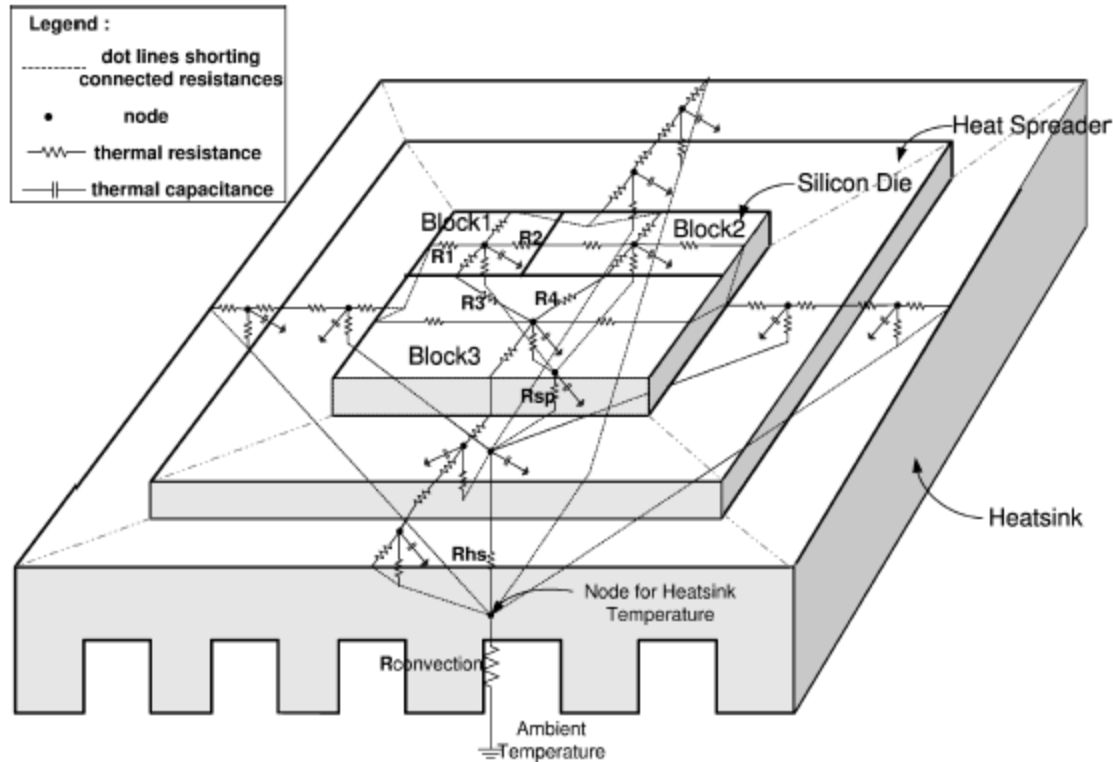


Low power pressure



Medium - high power pressure

# Thermal Model

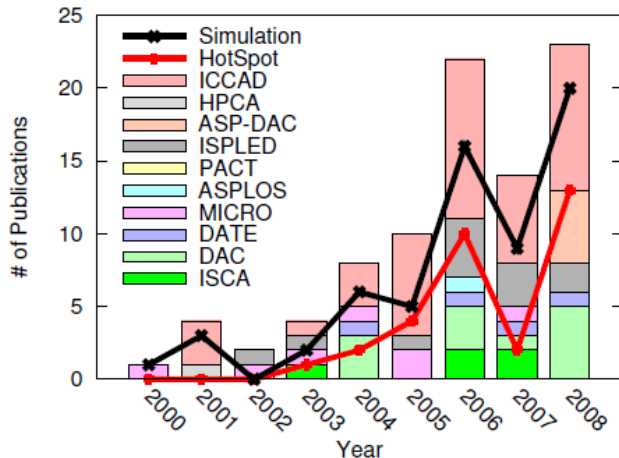
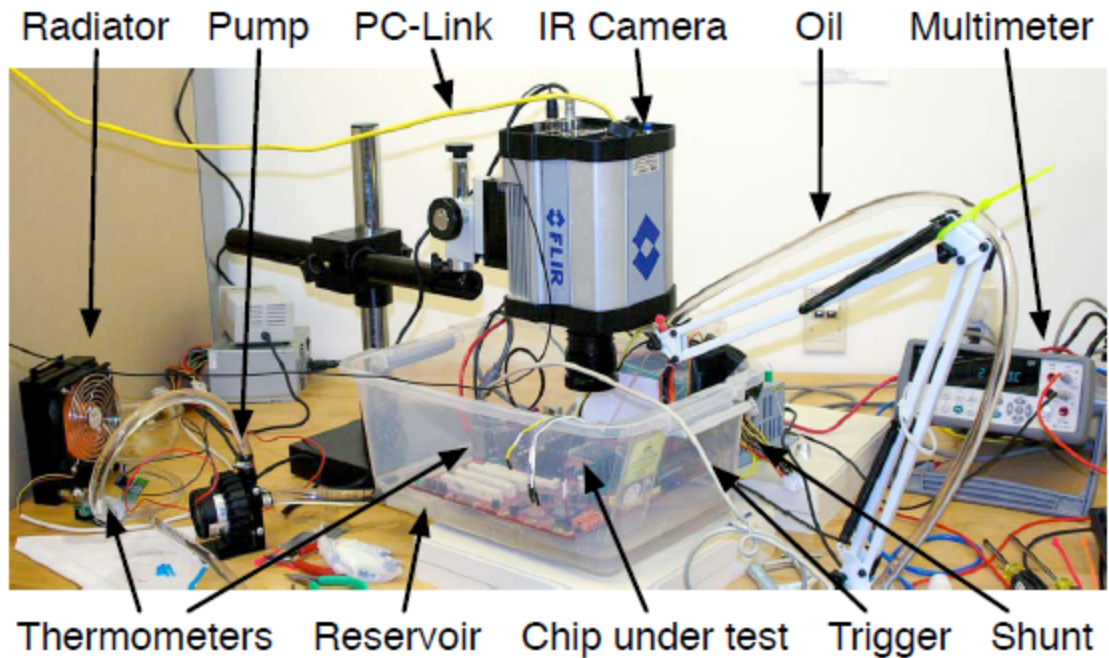


- Thermal behavior is modeled using RC circuit



# Temperature Map Measurements

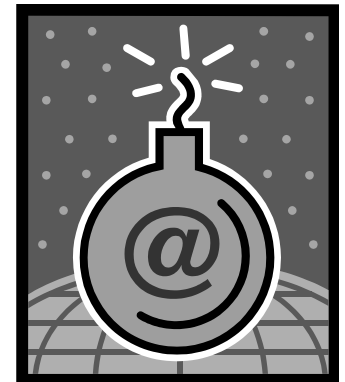
- Use IR camera (Jose Renau, UCSC)

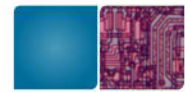




# Power Virus

- Maximum power consumption code
- How?
  - Use data from L1 or L2
  - Pipelines and queues are maintained full
  - For longer period (meaningful program





# Other Issues

- Power consumption
  - Not only CPUs
  - Memory, I/O devices, other units